



Board Characteristics

- All dimensions are given in inches unless specified otherwise.
- Material FR4 with Tg>170C, E.g. FR406
- Minimum trace width: 0.006" and clearance: 0.005" on Signal 1,6 (Top and Bottom);
- Minimum trace width and clearance: 0.005" on Signal 2,3,4,5,7,8,9,10 (all stripline);
- 1 oz copper for all power layers and for Signal 1,2 (Top and Bottom)  
1/2 oz copper for Stripline trace layers (Signal 2,3,4,5,7,8,9,10).
- Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.  
Apply Solder Mask over bare copper.
- Board Thickness: 0.093 +/- 0.008
- Mill the Top and Bottom of board on the solder side to a thickness of 0.063" +/- 0.008
- Silkscreen on Component and Solder Sides.
- 45 degree chamfer.
- FHS tolerances: +/- 0.002 unless specified otherwise.
- Interlayer spacing as specified
- Zc=55 Ohm +/- 5 Ohm for 0.005" stripline and 0.006" microstrip traces on all layers.  
Perform TDR test for all signal layers.  
Present TDR test results for all signal layers.

BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	4192	YES	---	
⊞	.015748031	144	YES	---	
⊕	.018	6	YES	---	
⊞	.035	10	YES	---	
⊖	.037	18	YES	---	
⊞	.041	420	YES	---	
⊕	.042	20	YES	---	
□	.052	80	YES	---	
	.057	20	YES	---	
	.062	4	YES	---	
	.062992126	2	YES	---	
	.086614173	2	NO	---	
	.106	6	NO	---	
	.12795276	2	YES	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES :XX :XXX DO NOT SCALE DRAWING		CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP		
TREATMENT		APPROVALS	DATE	TITLE 14-BIT ADC Board Specification Drawing		
FINISH		DRAWN M. Bogdan	1/21/15	SIZE B	FSCM NO.	DWG. NO. 2606-LEMO
SIMILAR TO		CHECKED M. Bogdan	1/21/15	ISSUED	REV. LEMO	
ACT. WT	CALC WT	SCALE 1/2		SHEET		